

June 2011

NC7SZ18 TinyLogic[®] UHS 1-of-2 Non-Inverting De-multiplexer with 3-STATE Deselected Output

Features

- Ultra-High Speed: t_{PD} 2.5ns Typical at 5V V_{CC}
- High Impedance Output when Deselected
- Broad V_{CC} Operating Range: 1.65V to 5.50V
- Power Down High Impedance Inputs/Outputs
- Over-Voltage Tolerance Inputs Facilitate 5V to 3V Translation
- Proprietary Noise/EMI Reduction Circuitry
- Ultra-Small MicroPak[™] Packages

Description

The NC7SZ18 is a 1-of-2 non-inverting demultiplexer. The device will buffer the data on the A pin and pass to either output $\rm Y_0$ or $\rm Y_1$ dependent on whether state of the select pin (S) is LOW or HIGH respectively. The deselected output will be placed into a high impedance state. The device is fabricated with advanced CMOS technology to achieve ultra high speed with high output drive while maintaining low static power dissipation over a broad $\rm V_{CC}$ operating range. The device is specified to operate over the 1.65V to 5.5V $\rm V_{CC}$ operating range. The inputs and outputs are high impedance when $\rm V_{CC}$ is 0V. Inputs tolerate voltages up to 5.5V independent of $\rm V_{CC}$ operating range.

Ordering Information

Part Number	Top Mark	Package	Packing Method
NC7SZ18P6X	Z18	6-Lead SC70, EIAJ SC88 1.25mm Wide	3000 Units on Tape & Reel
NC7SZ18L6X	D5	6-Lead MicroPak™, 1.00mm Wide	5000 Units on Tape & Reel
NC7SZ18FHX	D5	6-Lead, MicroPak2™, 1x1mm Body, .35mm Pitch	5000 Units on Tape & Reel

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Pin Configurations

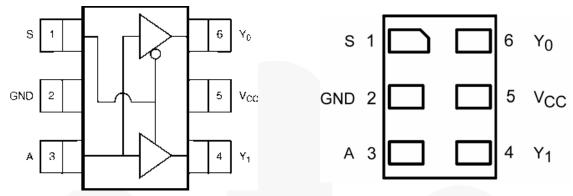


Figure 1. SC70 (Top View)

Figure 2. MicroPak™ (Top Through View)

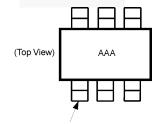


Figure 3. Pin 1 Orientation

Notes:

- 1. AAA represents product code top mark (see Ordering Information).
- 2. Orientation of top mark determines pin one location.
- 3. Reading the top mark left to right, pin one is the lower left pin.

Pin Definitions

Pin # SC70	Pin # MicroPak™	Name	Description
1	1	S	Data Input
2	2	GND	Ground
3	3	Α	Demultiplexer Data
4	4	Y ₁	Output
5	5	V _{cc}	Supply Voltage
6	6	Yo	Output

Function Table

Inp	outs	Output		
S	Α	Y ₀	Y ₁	
L	L	L	Z	
L	Н	Н	Z	
Н	L	Z	L	
Н	Н	Z	Н	

H = HIGH Logic Level

L = LOW Logic Level

X = 3-STATE

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Para	ameter	Min.	Max.	Unit
V _{CC}	Supply Voltage		-0.5	7.0	V
V _{IN}	DC Input Voltage		-0.5	7.0	V
V _{OUT}	DC Output Voltage		-0.5	7.0	V
I _{IK}	DC Input Diode Current	$V_{IN} \le -0.5V$		-50	mA
I _{OK}	DC Output Diode Current	V _{IN} ≤ -0.5V		-50	mA
I _{OUT}	DC Output Current			±50	mA
I _{CC} or I _{GND}	DC V _{CC} or Ground Current			±100	mA
T _{STG}	Storage Temperature Range		-65	+150	°C
TJ	Junction Temperature Under B	ias		+150	°C
TL	Junction Lead Temperature (So	oldering, 10 Seconds)		+260	°C
		SC70-6		180	
P_{D}	Power Dissipation at +85°C	MicroPak™-6		130	mW
		MicroPak2™-6		120	
ESD	Human Body Model, JEDEC:JE	ESD22-A114		4000	V
ESD	Charge Device Model, JEDEC:	JESD22-C101		2000	V

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Conditions	Min.	Max.	Unit
V	Supply Voltage Operating		1.65	5.50	V
V_{CC}	Supply Voltage Data Retention		1.5	5.5]
V_{IN}	Input Voltage		0	5.5	V
V _{OUT}	Output Voltage		0	V _{CC}	V
		V _{CC} at 1.8V, ±0.15V, 2.5V ± 0.2V	0	20	ns/V
t _r , t _f	Input Rise and Fall Times	V _{CC} at 3.3V ± 0.3V	0	10	
		V _{CC} at 5.0V ± 0.5V	0	5	
T _A	Operating Temperature		-40	+85	°C
		SC70-6		425	
θ_{JA}	Thermal Resistance	MicroPak™-6		500	°C/W
		MicroPak2™-6		560	

DC Electrical Characteristics

Symbol Parameter		V _{cc}	Condition	Т,	₄ =+25	°C		40 to 5°C	Unit	
				Min.	Тур.	Max.	Min.	Max.		
V _{IH}	HIGH Level Input	1.65 to 1.95		0.75V _{CC}			0.75V _{CC}		V	
VIH	Voltage	2.30 to 5.50		0.70V _{CC}			0.70V _{CC}		V	
V_{IL}	LOW Level Input	1.65 to 1.95				0.25V _{CC}		0.25V _{CC}	V	
V IL	Voltage	2.30 to 5.50				$0.30V_{CC}$		0.30V _{CC}	V	
		1.65		1.55	1.65		1.55			
		2.30	V _{IN} =V _{IH} ,	2.20	2.30		2.20			
		3.00	I _{OH} =-100μA	2.90	3.00		2.90			
		4.50		4.40	4.50		4.40			
V_{OH}	HIGH Level Output Voltage	1.65	I _{OH} =-4mA	1.29	1.52		1.29		V	
	Carpar voltage	2.30	I _{OH} =-8mA	1.90	2.15		1.90			
		3.00	I _{OH} =-16mA	2.40	2.80		2.40			
		3.00	I _{OH} =-24mA	2.30	3.68		2.30			
		4.50	I _{OH} =-32mA	3.80	4.20		3.80			
	/-	1.65			0.00	0.10		0.10		
		2.30	$V_{IN}=V_{IL}$		0.00	0.10		0.10		
		3.00	I _{OL} =100μA		0.00	0.10		0.10		
		4.50			0.00	0.10		0.10		
V_{OL}	LOW Level Output Voltage	1.65	I _{OL} =4mA		0.08	0.24		0.24	V	
	Carpar Voltago	2.30	I _{OL} =8mA		0.10	0.30		0.30		
		3.00	I _{OL} =16mA		0.15	0.40		0.40		
		3.00	I _{OL} =24mA		0.22	0.55		0.55		
		4.50	I _{OL} =32mA	37	0.22	0.55		0.55		
I _{IN}	Input Leakage Current	0 to 5.5	V _{IN} =5.5V, GND			±0.1		±1.0	μA	
l _{oz}	3-STATE Output Leakage	1.65 to 5.50	$V_{IN}=V_{IL}$ or V_{OH} 0< $V_{OUT} \le 5.5V$			±0.5		±5.0	μΑ	
I _{OFF}	Power Off Leakage Current	0	V _{IN} or V _{OUT} =5.5V			1		10	μΑ	
I _{cc}	Quiescent Supply Current	1.65 to 5.50	V _{IN} =5.5V, GND			1		10	μΑ	

AC Electrical Characteristics

Symbol Parameter		V _{cc}	V _{cc} Condition		T _A =+25°C		C	T _A =-40 to +85°C		Unit	Figure
,				Min.	Тур.	Max.	Min.	Max.			
		1.80 ± 0.15		2.0	6.3	10.1	2.0	10.5			
		2.50 ± 0.20	C _L =15pF,	1.0	3.6	5.7	1.0	6.0			
	Propagation Delay	3.30 ± 0.30	$R_D=1M\Omega$, $V_1=OPEN$	0.8	2.7	4.0	0.8	4.3		Figure 4	
t_{PLH}, t_{PHL}	A to Y ₀ or Y ₁	5.00 ± 0.50	·	0.5	2.0	3.1	0.5	3.3	ns	Figure 6	
		3.30 ± 0.30	C _L =50pF,	1.2	3.4	4.9	1.2	5.4			
		5.00 ± 0.50	R_D =500Ω, V ₁ =OPEN	0.8	2.5	3.9	8.0	4.2			
		1.80 ± 0.15		3.0	6.9	12.0	3.0	12.5			
		2.50 ± 0.20	$\begin{array}{l} R_{D}, R_{U} = 500\Omega, \\ V_{1} = GND \text{ for} \\ t_{PZH} \\ V_{1} = V_{IN} \text{ for} \\ t_{PZL} \\ V_{IN} = 2 \text{ x } V_{CC} \end{array}$	1.8	4.2	6.8	1.8	7.3	ns	Figure 4 Figure 6	
	Output Enable	3.30 ± 0.30		1.2	3.2	5.0	1.2	5.5			
	Time	5.00 ± 0.50		0.8	2.5	4.0	0.8	4.3			
t_{PZL}, t_{PHZ}	y y	1.80 ± 0.15	/	2.5	6.0	10.0	2.5	10.5			
		2.50 ± 0.20	$R_{D,}R_{U}=500\Omega$, $V_{1}=GND$ for	1.5	4.0	6.8	1.5	7.1	1		
	Output Disable Time	3.30 ± 0.30	t _{PHZ}	0.8	2.9	4.9	0.8	5.3	ns	Figure 4	
Time	5.00 ± 0.50	$V_1=V_{IN}$ for t_{PLZ} $V_{IN}=2 \times V_{CC}$	0.3	1.8	3.5	0.3	3.7		Figure 6		
C _{IN}	Input Capacitance	0			2.5				pF		
C _{OUT}	Output Capacitance	0			4.0				pF		
	Power Dissipation	3.30			16.0				~F	Figure 5	
C_{PD}	Capacitance ⁽⁴⁾	5.00			19.5				pF	Figure 5	

Note:

4. C_{PD} is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I_{CCD}) at no output loading and operating at 50% duty cycle. C_{PD} is related to I_{CCD} dynamic operating current by the expression: $I_{CCD} = (C_{PD})(V_{CC})(f_{IN}) + (I_{CC} \text{static})$.

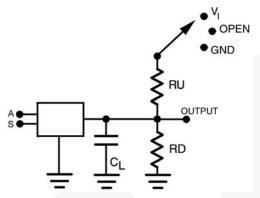
 V_{CC}

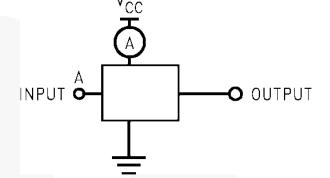
GND

VoL

 V_{OH}

AC Loadings and Waveforms





Notes:

- 5. C_L includes load and stray capacitance.
- 6. Input PRR = 1.0MHz, $t_W = 500$ ns.

Figure 4. AC Test Circuit

Figure 5. I_{CCD} Test Circuit

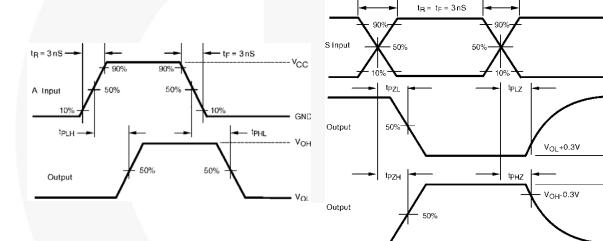


Figure 6. AC Waveforms

Physical Dimensions

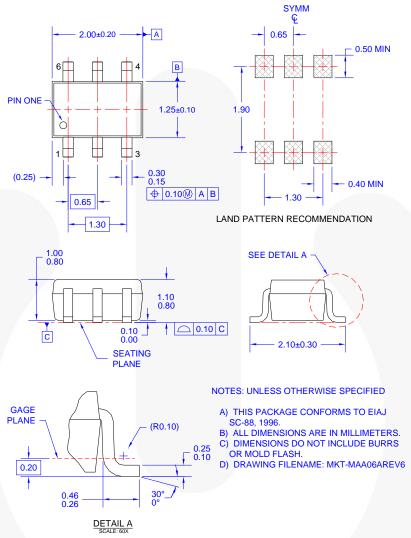


Figure 7. 6-Lead, SC70, EIAJ SC88, 1.25mm Wide

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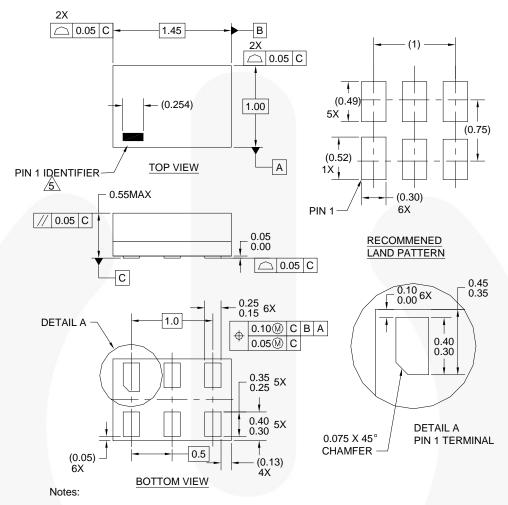
Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings: http://www.fairchildsemi.com/packaging/.

Tape and Reel Specification

Please visit Fairchild Semiconductor's online packaging area for the most recent tape and reel specifications: http://www.fairchildsemi.com/products/analog/pdf/sc70-6_tr.pdf.

Package Designator	Tape Section	Cavity Number	Cavity Status	Cover Type Status
	Leader (Start End)	125 (Typical)	Empty	Sealed
P6X	Carrier	3000	Filled	Sealed
	Trailer (Hub End)	75 (Typical)	Empty	Sealed

Physical Dimensions



- 1. CONFORMS TO JEDEC STANDARD M0-252 VARIATION UAAD
- 2. DIMENSIONS ARE IN MILLIMETERS
 3. DRAWING CONFORMS TO ASME Y14.5M-1994
- 4. FILENAME AND REVISION: MAC06AREV4
- 5. PIN ONE IDENTIFIER IS 2X LENGTH OF ANY

OTHER LINE IN THE MARK CODE LAYOUT.

Figure 8. 6-Lead, MicroPak™, 1.0mm Wide

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Tape and Reel Specification

Please visit Fairchild Semiconductor's online packaging area for the most recent tape and reel specifications: http://www.fairchildsemi.com/products/logic/pdf/micropak_tr.pdf.

Package Designator	Tape Section	Cavity Number	Cavity Status	Cover Type Status
	Leader (Start End)	125 (Typical)	Empty	Sealed
L6X	Carrier	5000	Filled	Sealed
	Trailer (Hub End)	75 (Typical)	Empty	Sealed

Physical Dimensions

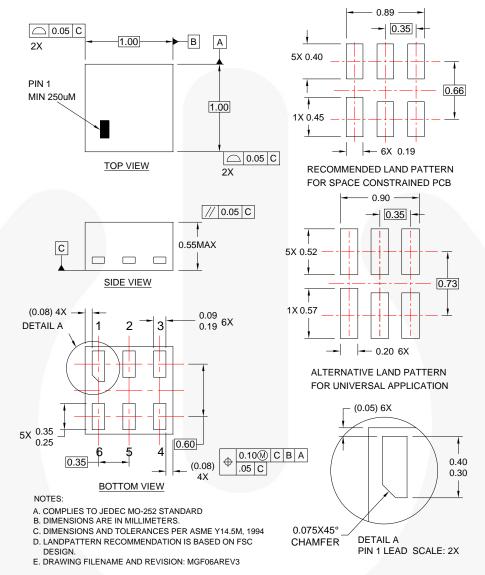


Figure 9. 6-Lead, MicroPak2™, 1x1mm Body, .35mm Pitch

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Tape and Reel Specification

Please visit Fairchild Semiconductor's online packaging area for the most recent tape and reel specifications: http://www.fairchildsemi.com/packaging/MicroPAK2_6L_tr.pdf.

Package Designator	Tape Section	Cavity Number	Cavity Status	Cover Type Status
	Leader (Start End)	125 (Typical)	Empty	Sealed
FHX	Carrier	5000	Filled	Sealed
	Trailer (Hub End)	75 (Typical)	Empty	Sealed





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